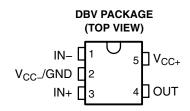
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- Low-Voltage and Single-Supply Operation
 V_{CC} = 2 V to 7 V
- Common-Mode Voltage Range Includes
 Ground
- Fast Response Time . . . 0.7 μs Typ
- Low Supply Current . . . 80 μA Typ and 150 μA Max
- Fully Specified at 3-V and 5-V Supply Voltages



description/ordering informaton

The TLV1391 is a differential comparator built using a Texas Instruments low-voltage, high-speed bipolar process. These devices have been developed specifically for low-voltage, single-supply applications. Their enhanced performance makes them excellent replacements for the LM393 in the improved 3-V and 5-V system designs.

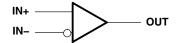
The TLV1391, with its typical supply current of only 80 μ A, is ideal for low-power systems. Response time also has been improved to 0.7 μ s.

ORDERING INFORMATION

T _A	PACKAGE	<u>:</u> †	ORDERABLE PART NUMBER	TOP-SIDE MARKING [‡]
000 to 7000	COT OO F (DD)/\	Reel of 3000	TLV1391CDBVR	Van
−0°C to 70°C	SOT-23-5 (DBV)	Reel of 250	TLV1391CDBVT	Y3D_
4000 to 0500	COT OO F (DD)/\	Reel of 3000	TLV1391IDBVR	Voc
-40°C to 85°C	SOT-23-5 (DBV)	Reel of 250	TLV1391IDBVT	Y3E_

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

symbol (each comparator)



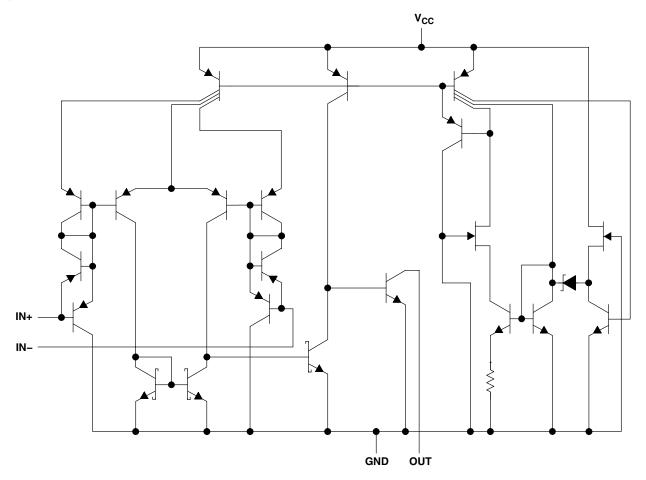


Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



[‡] The actual top-side marking has one additional character that designates the wafer fab/assembly site.

equivalent schematic



COMPONENT COUNT						
Transistors	26					
Resistors	1					
Diodes	4					
Epi-FET	1					



TLV1391 SINGLE DIFFERENTIAL COMPARATORS

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V _{CC} (see Note 1)	7 V
Differential input voltage, V _{ID} (see Note 2)	±7 V
Input voltage range, V _I (any input)	–0.3 V to V _{CC}
Output voltage, V _O	7 V
Output current, IO (each output)	20 mA
Duration of short-circuit current to GND (see Note 3)	Unlimited
Package thermal impedance, θ _{JA} (see Note 4 and 5)	206°C/W
Operating virtual junction temperature, T _J	150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C
Storage temperature range, T _{stg}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. All voltage values, except differential voltages, are with respect to the network GND.
 - 2. Differential voltages are at the noninverting input with respect to the inverting input.
 - 3. Short circuits from the outputs to V_{CC} can cause excessive heating and eventual destruction of the chip.
 - 4. Maximum power dissipation is a function of $T_J(max)$, θ_{JA} , and T_A . The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(max) T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can impact reliability.
 - 5. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions

			MIN	MAX	UNIT
V _{CC}	Supply voltage		2	7	V
_	Operating free-air temperature	391C	0	70	00
1A	TLV13	3911	-40	85	°C



TLV1391 SINGLE DIFFERENTIAL COMPARATORS

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electrical characteristics, $V_{CC} = 3 V$

	PARAMETER	TEST	CONDITIONS	T _A	MIN	TYP	MAX	UNIT
\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	land offertualte as	V 44V	V V (main)	25°C		1.5	5	V
V _{IO}	Input offset voltage	$V_0 = 1.4 V,$	$V_{IC} = V_{ICR}(min)$	Full range			9	mV
V				25°C	0 to V _{CC} -1.5	0 to V _{CC} -1.2		٧
V _{ICR}	Common-mode input voltage range			Full range	0 to V _{CC} -2			V
V_{OL}	Low-level output voltage	$V_{ID} = -1 V$,	$I_{OL} = 500 \mu A$	Full range		120	300	mV
	land offers surrent	V 44V		25°C		5	50	4
I _{IO}	Input offset current	$V_0 = 1.4 \text{ V}$		Full range			150	nA
				25°C		-40	-250	
I _{IB}	Input bias current	$V_0 = 1.4 \text{ V}$		Full range			-400	nA
		$V_{ID} = 1 V$,	V _{OH} = 3 V	25°C		0.1		
Іон	High-level output current	$V_{ID} = 1 V$,	V _{OH} = 5 V	Full range			100	nA
I _{OL}	Low-level output current	$V_{ID} = -1 V$,	V _{OL} = 1.5 V	25°C	500			μΑ
		,, ,,		25°C		80	125	
I _{CC(H)}	High-level supply current	$V_O = V_{OH}$		Full range			150	μ A
	Low lovel cumby cumont	V V		25°C		80	125	
I _{CC(L)}	Low-level supply current	$V_O = V_{OL}$		Full range			150	μΑ

switching characteristics, V_{CC} = 3 V, C_L = 15 pF $^\dagger,\,T_A$ = 25 $^\circ C$

PARAMETER	TEST CONDITION	TEST CONDITIONS				
Response time	100-mV input step with 5-mV overdrive,	$R_L = 5.1 \text{ k}\Omega$	0.7	μs		

[†] C_L includes the probe and jig capacitance.



electrical characteristics, $V_{CC} = 5 V$

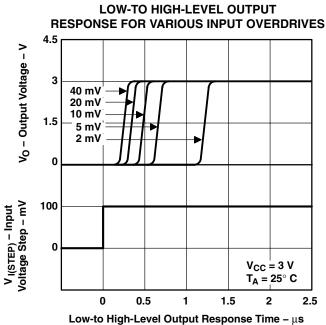
	PARAMETER	TEST	CONDITIONS	T _A	MIN	TYP	MAX	UNIT	
\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	land offertualtens	V 44V	V V (main)	25°C		1.5	5	\/	
V _{IO}	Input offset voltage	$V_0 = 1.4 V,$	$V_{IC} = V_{ICR}(min)$	Full range			9	mV	
V				25°C	0 to V _{CC} -1.5	0 to V _{CC} -1.2		V	
V _{ICR}	Common-mode input voltage range			Full range	0 to V _{CC} -2			V	
V_{OL}	Low-level output voltage	$V_{ID} = -1 V$,	$I_{OL} = 500 \mu A$	Full range		120	300	mV	
l .	land offers surrent	V 44V		25°C		5	50	A	
I _{IO}	input offset current	Input offset current	$V_0 = 1.4 \text{ V}$		Full range			150	nA
	land the annual to	V 44V		25°C		-40	-250	A	
I _{IB}	Input bias current	$V_0 = 1.4 \text{ V}$		Full range			-400	nA	
	I Park Tarrel and and annual	$V_{ID} = 1 V$,	V _{OH} = 3 V	25°C		0.1		A	
Іон	High-level output current	$V_{ID} = 1 V$,	V _{OH} = 5 V	Full range			100	nA	
I _{OL}	Low-level output current	$V_{ID} = -1 V$,	V _{OL} = 1.5 V	25°C	600			μΑ	
	High level events events	V V		25°C		100	150		
I _{CC(H)}	High-level supply current	$V_O = V_{OH}$		Full range			175	μΑ	
	Low lovel cumby cumont	V V		25°C		100	150		
I _{CC(L)}	Low-level supply current	$V_O = V_{OL}$		Full range			175	μΑ	

switching characteristics, V_{CC} = 5 V, C_L = 15 pF†, T_A = 25°C

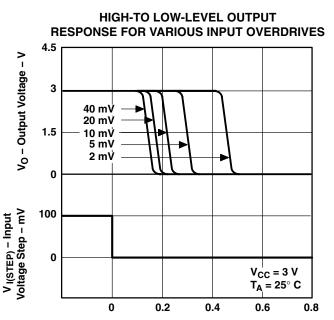
PARAMETER	TEST CONDITIONS	TYP	UNIT	
Deenenes time	100-mV input step with 5-mV overdrive,	$R_L = 5.1 \text{ k}\Omega$	0.65	
Response time	TTL-level input step,	$R_L = 5.1 \text{ k}\Omega$	0.18	μs

[†] C_L includes the probe and jig capacitance.

TYPICAL CHARACTERISTICS







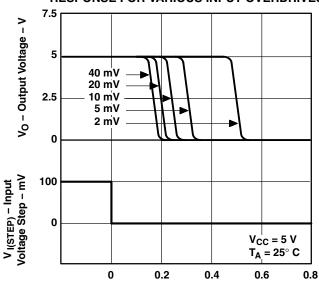
High-to Low-Level Output Response Time – μs

Figure 2

LOW-TO HIGH-LEVEL OUTPUT RESPONSE FOR VARIOUS INPUT OVERDRIVES 7.5 V_O - Output Voltage - V 5 40 mV 20 mV 10 mV 2.5 5 mV 2 mV 0 V_{I(STEP)} – Input Voltage Step – mV 100 0 $V_{CC} = 5 V$ T_A = 25° C 1 1.5 0 0.5 2.5 Low-to High-Level Output Response Time – μ s

Figure 3

HIGH-TO LOW-LEVEL OUTPUT RESPONSE FOR VARIOUS INPUT OVERDRIVES



High-to Low-Level Output Response Time – μs Figure 4



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PACKAGING INFORMATION

Orderable part number	Status (1)	Material type	Package Pins	Package qty Carrier	RoHS	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
TLV1391CDBVR	Active	Production	SOT-23 (DBV) 5	3000 LARGE T&R	Yes	NIPDAU SN	Level-1-260C-UNLIM	0 to 70	(1391, Y3D6, Y3DG, Y3DJ)
TLV1391CDBVR.A	Active	Production	SOT-23 (DBV) 5	3000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	(1391, Y3D6, Y3DG, Y3DJ)
TLV1391CDBVR1G4	Active	Production	SOT-23 (DBV) 5	3000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	1391
TLV1391CDBVR1G4.A	Active	Production	SOT-23 (DBV) 5	3000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	1391
TLV1391CDBVRG4	Obsolete	Production	SOT-23 (DBV) 5	-	-	Call TI	Call TI	0 to 70	Y3DG
TLV1391IDBVR	Active	Production	SOT-23 (DBV) 5	3000 LARGE T&R	Yes	NIPDAU SN	Level-1-260C-UNLIM	-40 to 85	(1391, Y3E6, Y3EB, Y3EJ)
TLV1391IDBVR.A	Active	Production	SOT-23 (DBV) 5	3000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	(1391, Y3E6, Y3EB, Y3EJ)
TLV1391IDBVRG4	Active	Production	SOT-23 (DBV) 5	3000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	(1391, Y3E6, Y3EB)
TLV1391IDBVRG4.A	Active	Production	SOT-23 (DBV) 5	3000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	(1391, Y3E6, Y3EB)

⁽¹⁾ Status: For more details on status, see our product life cycle.

⁽²⁾ Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

⁽⁴⁾ Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.



PACKAGE OPTION ADDENDUM

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Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION



TAPE DIMENSIONS KO P1 BO W Cavity A0

A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TLV1391CDBVR	SOT-23	DBV	5	3000	180.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
TLV1391CDBVR	SOT-23	DBV	5	3000	180.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
TLV1391CDBVR1G4	SOT-23	DBV	5	3000	180.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
TLV1391IDBVR	SOT-23	DBV	5	3000	180.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
TLV1391IDBVR	SOT-23	DBV	5	3000	180.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
TLV1391IDBVRG4	SOT-23	DBV	5	3000	180.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3



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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TLV1391CDBVR	SOT-23	DBV	5	3000	210.0	185.0	35.0
TLV1391CDBVR	SOT-23	DBV	5	3000	210.0	185.0	35.0
TLV1391CDBVR1G4	SOT-23	DBV	5	3000	210.0	185.0	35.0
TLV1391IDBVR	SOT-23	DBV	5	3000	210.0	185.0	35.0
TLV1391IDBVR	SOT-23	DBV	5	3000	210.0	185.0	35.0
TLV1391IDBVRG4	SOT-23	DBV	5	3000	210.0	185.0	35.0



SMALL OUTLINE TRANSISTOR



NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
 2. This drawing is subject to change without notice.
 3. Reference JEDEC MO-178.

- 4. Body dimensions do not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.25 mm per side.
- 5. Support pin may differ or may not be present.



SMALL OUTLINE TRANSISTOR



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE TRANSISTOR



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



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